

Title (en)

CONTACT PLUG FOR DIRECTLY CONTACTING A CIRCUIT BOARD

Title (de)

KONTAKTIERUNGSSTECKER ZUR DIREKTKONTAKTIERUNG EINER LEITERPLATTE

Title (fr)

FICHE DE MISE EN CONTACT POUR LA MISE EN CONTACT DIRECTE D'UNE CARTE DE CIRCUITS IMPRIMÉS

Publication

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Application

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Abstract (en)

[origin: WO2012119830A1] The invention relates to a contact plug (40) for directly electrically connecting contact surfaces (3) disposed on both sides of a circuit board (2), having two contact carriers (6) joined to each other with a hinge and forming a plug receptacle (7) between said carriers for the circuit board (2) and each comprising at least one contact element protruding into the plug receptacle (7), and having a spring (9), the two free contact tongues (9a) thereof extending past the two contact carriers (6) in the plug direction (4) of the contact plug (1) and being pretensioned in the direction toward each other, and having a control channel (10) formed between the two contact carriers (6) and laterally adjacent to the plug receptacle (7), said control channel interacting with a control wedge (11) provided on the circuit board (2) for pivoting the two contact carriers (6) against the action of the spring (9) when the circuit board (2) is inserted, and having a seal (13) sealing the back sides of the two contact carriers (6) in a mating contact plug (15), wherein according to the invention the two free contact tongues (9a) of the spring (9) extend past the two contact carriers (6) in the plug direction (4) of the contact plug (40), and the seal (13) is disposed between the contact carriers (6) and the center spring segment (9b) of the spring (9), wherein the two contact tongues (9a) extend through the seal (13) and are sealed at the seal (13).

IPC 8 full level

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